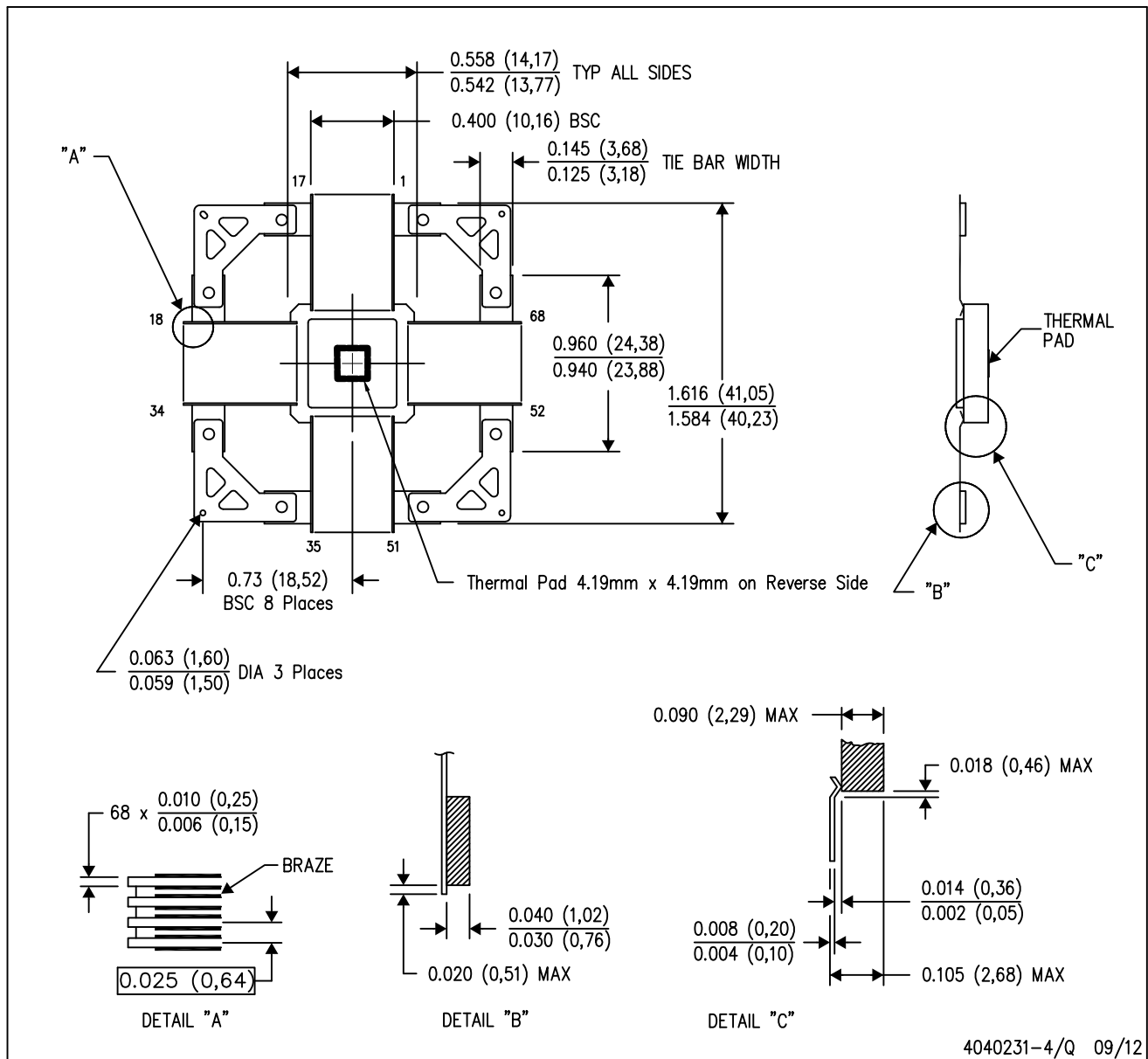


HFG (S-CQFP-F68)

CERAMIC QUAD FLATPACK WITH NCTB



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
 - D. This package is hermetically sealed with a metal lid.
 - E. The leads are gold plated and can be solderdipped.
 - F. Leads not shown for clarity purposes.
 - G. Thermal dissipation enhancement provided by vias to external bottom pad.
 - H. Lid and Thermal pad are connected to GND leads.

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